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(IWLPC 2013)

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IWLPC 2013 PROGRAM | November 6-7, 2013

Wednesday, November 6th

WLP TRACK

Session 1 – Wafer-Level Automation & Test

3D TRACK

Session 2 – Thermo-Compression Bonding for 3D Packaging

MEMS TRACK

Session 3 – Wafer-Level Packaged MEMS

WLP TRACK

Session 4 – Wafer-Level Materials

IWLPC 2013 PROGRAM | November 6-7, 2013

Thursday, November 7th

WLP TRACK

Session 7 – Wafer-Level Process

3D TRACK

Session 8 – Interposers

3D TRACK

Session 9 –3D Metrology and Test

WLP TRACK

Session 10 - Fan-Out Wafer-Level Packaging Technologies